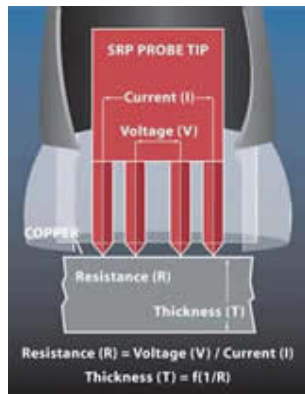


微電阻量測原理



Microresistance technique used to measure copper in plated-thru-holes after etch as well as copper on the surface of printed circuit boards

The new micro-resistance method of determining plating thickness is ideally suited for printed circuit board plated-thru-holes and for surface copper measurements.

This technique requires precise measurement of the resistance of the copper cylinder that forms the plated thru-hole. Once this parameter is known, it is combined with data on the board and hole aspect ratio to calculate the average copper plating thickness. Calculations are performed automatically by software associated with the measurement device.

Specially designed, pyramidal, electrically isolated probe tips simultaneously inject current and take voltage-drop measurements. The resistance is then calculated by Ohm's Law.